

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Packaging	Typical Dimension mm(inches)
1	IC1	1	—	TCK301G TCK302G TCK303G	TOSHIBA	Load Switch IC	WCSP9	1.5 x 1.5
2	R1	1	10kΩ			Carbon, ±5%	—	1.0 x 0.5 (0402)
3	C1	1	1μF			Ceramic, 50V, ±10%	—	3.2 x 1.6 (1206)
4	C2	1	1μF			Ceramic, 50V, ±10%	—	3.2 x 1.6 (1206)

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